

Trevor Braun

List of Publications by Year in descending order

Source: <https://exaly.com/author-pdf/7075353/publications.pdf>

Version: 2024-02-01

21
papers

262
citations

1040056

9
h-index

940533

16
g-index

21
all docs

21
docs citations

21
times ranked

224
citing authors

#	ARTICLE	IF	CITATIONS
1	The Emerging Role of Electrodeposition in Additive Manufacturing. <i>Electrochemical Society Interface</i> , 2016, 25, 69-73.	0.4	34
2	Effect of Chloride Concentration on Copper Deposition in Through Silicon Vias. <i>Journal of the Electrochemical Society</i> , 2019, 166, D3259-D3271.	2.9	32
3	Localized Electrodeposition and Patterning Using Bipolar Electrochemistry. <i>Journal of the Electrochemical Society</i> , 2015, 162, D180-D185.	2.9	31
4	A High-Throughput Structural and Electrochemical Study of Metallic Glass Formation in Ni-Ti-Al. <i>ACS Combinatorial Science</i> , 2020, 22, 330-338.	3.8	31
5	Editors' Choice—Simulation of Copper Electrodeposition in Through-Hole Vias. <i>Journal of the Electrochemical Society</i> , 2020, 167, 013510.	2.9	23
6	Superconformal Nickel Deposition in Through Silicon Vias: Experiment and Prediction. <i>Journal of the Electrochemical Society</i> , 2018, 165, D291-D300.	2.9	22
7	High-Aspect-Ratio Ag Nanowire Mat Electrodes for Electrochemical CO ₂ Production from CO ₂ . <i>ACS Catalysis</i> , 2021, 11, 11945-11959.	11.2	20
8	Simulating the Influence of Supporting Electrolyte Concentration on Copper Electrodeposition in Microvias. <i>Journal of the Electrochemical Society</i> , 2022, 169, 012502.	2.9	12
9	Bipolar Electrochemical Displacement: A New Phenomenon with Implications for Self-Limiting Materials Patterning. <i>ChemElectroChem</i> , 2016, 3, 441-449.	3.4	10
10	Microelectrode Studies of S-NDR Copper Electrodeposition: Potentiodynamic and Galvanodynamic Measurements and Simulations. <i>Journal of the Electrochemical Society</i> , 2020, 167, 082509.	2.9	10
11	Simulating Cu electrodeposition in high aspect ratio features: Effect of control mode and uncompensated resistance in S-NDR systems. <i>Electrochimica Acta</i> , 2021, 375, 137925.	5.2	8
12	Effect of Chloride on Microstructure in Cu Filled Microscale Through Silicon Vias. <i>Journal of the Electrochemical Society</i> , 2021, 168, 112501.	2.9	6
13	Mapping Surface Chemistry During Superfilling with Shell-Isolated Nanoparticle Enhanced Raman Spectroscopy and X-ray Photoelectron Spectroscopy. <i>Journal of the Electrochemical Society</i> , 2022, 169, 082506.	2.9	6
14	Simulation of Copper Electrodeposition in Millimeter Size Through-Silicon Vias. <i>Journal of the Electrochemical Society</i> , 2020, 167, 162508.	2.9	5
15	Remote Control Electrodeposition: Principles for Bipolar Patterning of Substrates without an Electrical Connection. <i>Journal of the Electrochemical Society</i> , 2016, 163, D3014-D3019.	2.9	3
16	Analytical and Computational Scaling Relationships for the Coupled Phenomena that Control Local Bipolar Electrochemical Behavior. <i>Journal of the Electrochemical Society</i> , 2016, 163, E354-E362.	2.9	3
17	Exploring the Kinetic and Thermodynamic Relationship of Charge Transfer Reactions Used in Localized Electrodeposition and Patterning in a Scanning Bipolar Cell. <i>Frontiers in Chemistry</i> , 2019, 7, 340.	3.6	3
18	Microstructure and Texture in Copper Filled Millimeter Scale Through Silicon Vias. <i>Journal of the Electrochemical Society</i> , 2022, 169, 032508.	2.9	2

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19	Effect of Chloride Concentration on Copper Deposition in Through Silicon Vias. Journal of the Electrochemical Society, 2019, 166, .	2.9	1
20	Superconformal Nickel Deposition in Through Silicon Vias: Experiment and Prediction. Journal of the Electrochemical Society, 2018, 165, .	2.9	0
21	Simulation of Copper Electrodeposition in Through-Hole Vias. Journal of the Electrochemical Society, 2020, 167, .	2.9	0